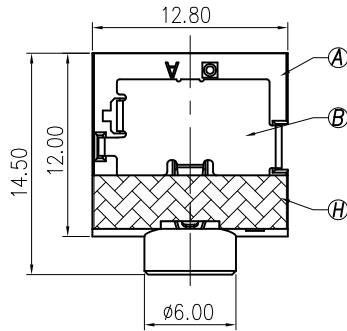
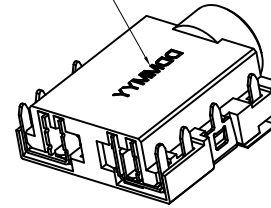
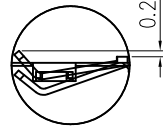


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	BILLY	2011.12.30
B	ECN NO.:C140074 MODIFY LAYOUT	ZLS	2014.8.12

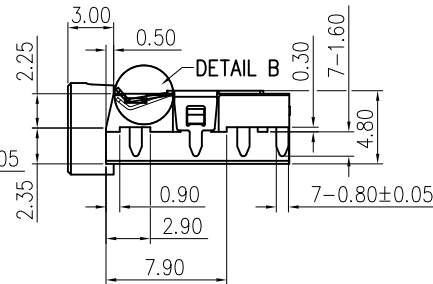
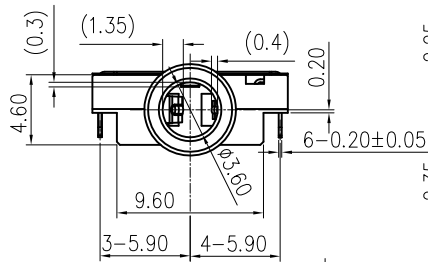
DATE CODE



DETAIL B SCALE 2:1



Product application:
The Shell spring working position when Plug-In.



SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:

- 1-1. RATING: 36V, 1A.
- 1-2. CONTACT RESISTANCE: 50mΩ MAX.
- 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
- 1-4. INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC

2. MECHANICAL CHARACTERISTICS:

- 2-1. INSERTION FORCE : 0.4~3.0 KGF
- 2-2. WITHDRAWAL FORCE : 0.3~2.0 KGF

3. LIFE TEST: 5,000 CYCLES MIN.

4. OTHER GENERAL SPEC. TO REFER "2SJ2285 SERIES SPEC".

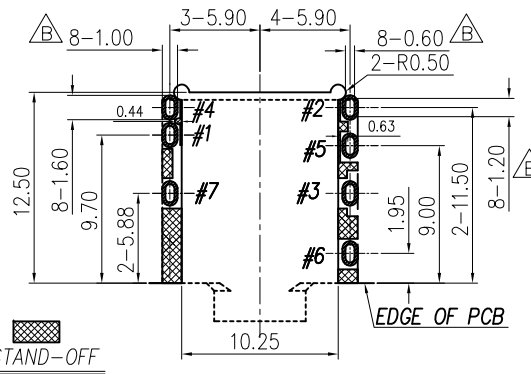
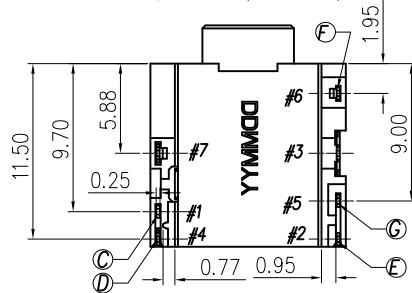
5. TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.

6. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:

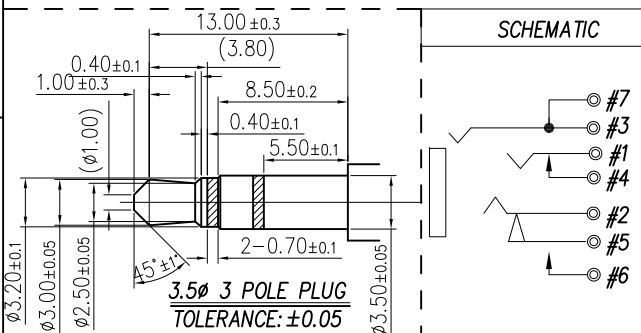
7. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:

8. FOR REFLOW SOLDERING LEAD-FREE PROCESS.

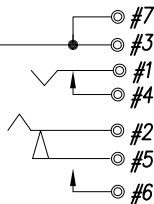
9. PACKAGING: TAPE&REEL.



RECOMMENDED P.C.B. LAYOUT T=1.20
TOP VIEW (TOLRANCE: ±0.05)



SCHEMATIC



H	MYLAR	1	MYLAR 0.75T	
G	TRANSFER TERMINAL	1	COPPER ALLOY 0.20T	Gold Flash on contact area and Solder tail all over Nickel Plating
F	MAKE TERMINAL	1	COPPER ALLOY 0.20T	GOLD FLASH
E	RING	1	COPPER ALLOY 0.20T	Gold Flash on contact area and Solder tail all over Nickel Plating
D	SHUNT	1	COPPER ALLOY 0.20T	GOLD FLASH
C	TIP	1	COPPER ALLOY 0.25T	Gold Flash on contact area and Solder tail all over Nickel Plating
B	SHIELD	1	COPPER ALLOY 0.20T	NI PLATING
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

DECIMALS:	ANGLES:	TITLE	3.5φ PHONE JACK		
X : ±0.5	X : ±2°	DWN	14/8/19	PART NO. 2SJ2285-214252F	
X.X : ±0.3	X.X : ±1°	CHKD	14/8/19	SCALE 1:1	UNIT: mm
X.XX : ±0.2		APVD	14/8/19	SIZE: A3	SHEET: 10F1 REV:B

CUSTOMER COPY